

**TC74HC273AP, TC74HC273AF, TC74HC273AFW**

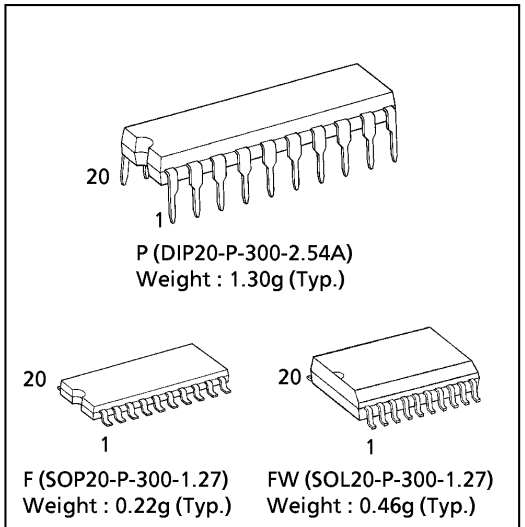
(Note) The JEDEC SOP (FW) is not available in Japan.

**OCTAL D-TYPE FLIP FLOP WITH CLEAR**

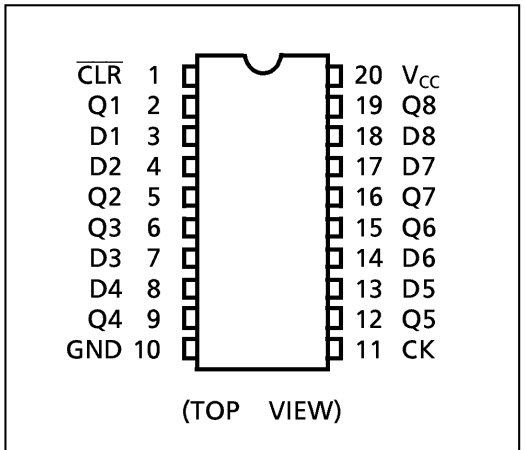
The TC74HC273A is a high speed CMOS OCTAL D-TYPE FLIP FLOP fabricated with silicon gate C<sup>2</sup>MOS technology. It achieves the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation. Information signals applied to D inputs are transferred to the Q outputs on the positive going edge of the clock pulse. When the  $\overline{\text{CLR}}$  input is held "L", the Q outputs are at a low logic level independent of the other inputs. All inputs are equipped with protection circuits against static discharge or transient excess voltage.

**FEATURES :**

- High Speed.....  $f_{\text{MAX}} = 67\text{MHz}(\text{typ.})$   
at  $V_{\text{CC}} = 5\text{V}$
- Low Power Dissipation.....  $I_{\text{CC}} = 4\mu\text{A}(\text{Max.})$  at  $T_a = 25^\circ\text{C}$
- High Noise Immunity.....  $V_{\text{NIH}} = V_{\text{NIL}} = 28\% V_{\text{CC}} (\text{Min.})$
- Output Drive Capability ..... 10 LSTTL Loads
- Symmetrical Output Impedance...  $|I_{\text{OH}}| = I_{\text{OL}} = 4\text{mA}(\text{Min.})$
- Balanced Propagation Delays.....  $t_{\text{PLH}} \approx t_{\text{PHL}}$
- Wide Operating Voltage Range...  $V_{\text{CC}} (\text{opr.}) = 2\text{V} \sim 6\text{V}$
- Pin and Function Compatible with 74LS273



**PIN ASSIGNMENT**

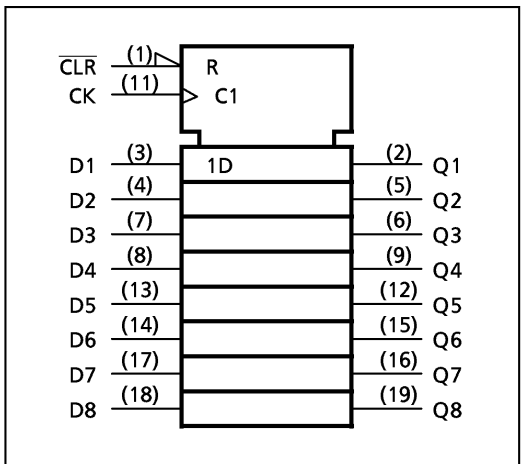


**TRUTH TABLE**

INPUTS			OUTPUTS	FUNCTION
$\overline{\text{CLR}}$	D	CK	Q	
L	X	X	L	CLEAR
H	L		L	—
H	H		H	—
H	X		Q <sub>n</sub>	No change

X : Don't Care

**IEC LOGIC SYMBOL**



## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	$V_{CC}$	$-0.5 \sim 7$	V
DC Input Voltage	$V_{IN}$	$-0.5 \sim V_{CC} + 0.5$	V
DC Output Voltage	$V_{OUT}$	$-0.5 \sim V_{CC} + 0.5$	V
Input Diode Current	$I_{IK}$	$\pm 20$	mA
Output Diode Current	$I_{OK}$	$\pm 20$	mA
DC Output Current	$I_{OUT}$	$\pm 25$	mA
DC $V_{CC}$ /Ground Current	$I_{CC}$	$\pm 50$	mA
Power Dissipation	$P_D$	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	$T_{stg}$	$-65 \sim 150$	$^{\circ}\text{C}$

\*500mW in the range of  $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$ . From  $T_a = 65^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  a derating factor of  $-10\text{mW}/^{\circ}\text{C}$  shall be applied until 300mW.

## RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	$V_{CC}$	$2 \sim 6$	V
Input Voltage	$V_{IN}$	$0 \sim V_{CC}$	V
Output Voltage	$V_{OUT}$	$0 \sim V_{CC}$	V
Operating Temperature	$T_{opr}$	$-40 \sim 85$	$^{\circ}\text{C}$
Input Rise and Fall Time	$t_r, t_f$	0~1000 ( $V_{CC} = 2.0\text{V}$ ) 0~500 ( $V_{CC} = 4.5\text{V}$ ) 0~400 ( $V_{CC} = 6.0\text{V}$ )	ns

## DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	$V_{CC}$ (V)	$T_a = 25^{\circ}\text{C}$			$T_a = -40 \sim 85^{\circ}\text{C}$		UNIT	
				MIN.	TYP.	MAX.	MIN.	MAX.		
High - Level Input Voltage	$V_{IH}$		2.0	1.50	—	—	1.50	—	V	
			4.5	3.15	—	—	3.15	—		
			6.0	4.20	—	—	4.20	—		
Low - Level Input Voltage	$V_{IL}$		2.0	—	—	0.50	—	0.50	V	
			4.5	—	—	1.35	—	1.35		
			6.0	—	—	1.80	—	1.80		
High - Level Output Voltage	$V_{OH}$	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OH} = -20\mu\text{A}$	2.0	1.9	2.0	—	1.9	—	V
				4.5	4.4	4.5	—	4.4	—	
			6.0	5.9	6.0	—	5.9	—		
			$I_{OH} = -4\text{ mA}$ $I_{OH} = -5.2\text{ mA}$	4.5	4.18	4.31	—	4.13	—	
				6.0	5.68	5.80	—	5.63	—	
			Low - Level Output Voltage	$V_{OL}$	$V_{IN} = V_{IH}$ or $V_{IL}$	$I_{OL} = 20\mu\text{A}$	2.0	—	0.0	
4.5	—	0.0					0.1	—	0.1	
6.0	—	0.0				0.1	—	0.1		
$I_{OL} = 4\text{ mA}$ $I_{OL} = 5.2\text{ mA}$	4.5	—				0.17	0.26	—	0.33	
	6.0	—				0.18	0.26	—	0.33	
Input Leakage Current	$I_{IN}$	$V_{IN} = V_{CC}$ or GND				6.0	—	—	$\pm 0.1$	—
Quiescent Supply Current	$I_{CC}$	$V_{IN} = V_{CC}$ or GND	6.0	—	—	4.0	—	40.0		

**TIMING REQUIREMENTS (Input  $t_r = t_f = 6ns$ )**

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C			Ta = -40~85°C		UNIT
			V <sub>CC</sub> (V)	TYP.	LIMIT	LIMIT		
Minimum Pulse Width (CK)	$t_{W(L)}$ $t_{W(H)}$		2.0	—	75	95	ns	
			4.5	—	15	19		
			6.0	—	13	16		
Minimum Pulse Width (CLR)	$t_{W(L)}$		2.0	—	75	95		
			4.5	—	15	19		
			6.0	—	13	16		
Minimum Set-up Time	$t_s$		2.0	—	75	95		
			4.5	—	15	19		
			6.0	—	13	16		
Minimum Hold Time	$t_h$		2.0	—	0	0		
			4.5	—	0	0		
			6.0	—	0	0		
Minimum Removal Time (CLR)	$t_{rem}$		2.0	—	50	65		
			4.5	—	10	13		
			6.0	—	9	11		
Clock Frequency	f		2.0	—	6	5	MHz	
			4.5	—	30	24		
			6.0	—	35	28		

**AC ELECTRICAL CHARACTERISTICS (C<sub>L</sub> = 15pF, V<sub>CC</sub> = 5V, Ta = 25°C, Input  $t_r = t_f = 6ns$ )**

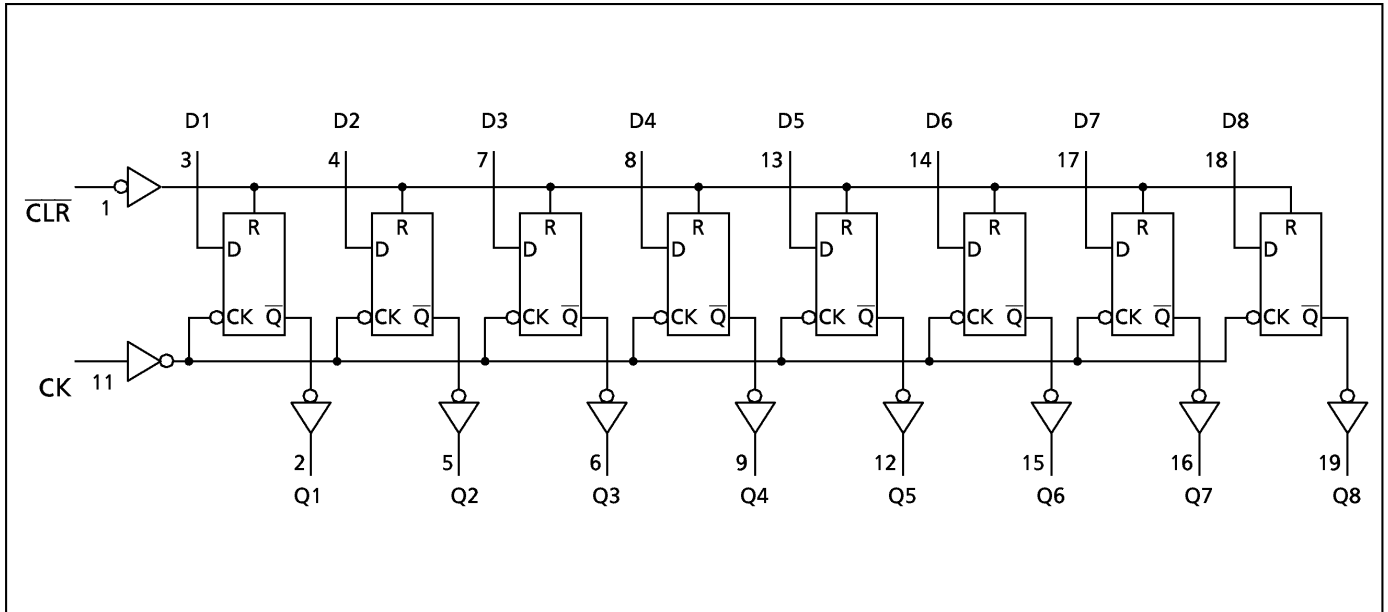
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Transition Time	$t_{TLH}$		—	4	8	ns
	$t_{THL}$					
Propagation Delay Time (CK-Q)	$t_{PLH}$		—	15	25	
	$t_{PHL}$					
Propagation Delay Time (CLR-Q)	$t_{PLH}$		—	16	27	
	$t_{PHL}$					
Maximum Clock Frequency	$f_{MAX}$		40	67	—	

**AC ELECTRICAL CHARACTERISTICS (C<sub>L</sub> = 50pF, Input  $t_r = t_f = 6ns$ )**

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C			Ta = -40~85°C		UNIT
			V <sub>CC</sub> (V)	MIN.	TYP.	MAX.	MIN.	
Output Transition Time	$t_{TLH}$ $t_{THL}$		2.0	—	25	75	—	95
			4.5	—	7	15	—	19
			6.0	—	6	13	—	16
Propagation Delay Time (CK-Q)	$t_{PLH}$ $t_{PHL}$		2.0	—	54	145	—	180
			4.5	—	18	29	—	36
			6.0	—	15	25	—	31
Propagation Delay Time (CLR-Q)	$t_{PLH}$ $t_{PHL}$		2.0	—	60	160	—	200
			4.5	—	20	32	—	40
			6.0	—	17	27	—	34
Maximum Clock Frequency	$f_{MAX}$		2.0	6	18	—	5	—
			4.5	30	56	—	24	—
			6.0	35	66	—	28	—
Input Capacitance	C <sub>IN</sub>		—	5	10	—	10	
Power Dissipation Capacitance	C <sub>PD</sub> (1)		—	43	—	—	—	

Note (1) C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.  
 Average operating current can be obtained by the equation :  
 $I_{CC(opr)} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 8$  (per Flip Flop)  
 And the total C<sub>PD</sub> when n pcs. of Flip Flop operate can be gained by the following equation :  
 $C_{PD}(total) = 32 + 11 \cdot n$

**SYSTEM DIAGRAM**



**DIP 20PIN PACKAGE DIMENSIONS (DIP20-P-300-2.54A)**

Unit in mm



**SOP 20PIN (200mil BODY) PACKAGE DIMENSIONS (SOP20-P-300-1.27)**

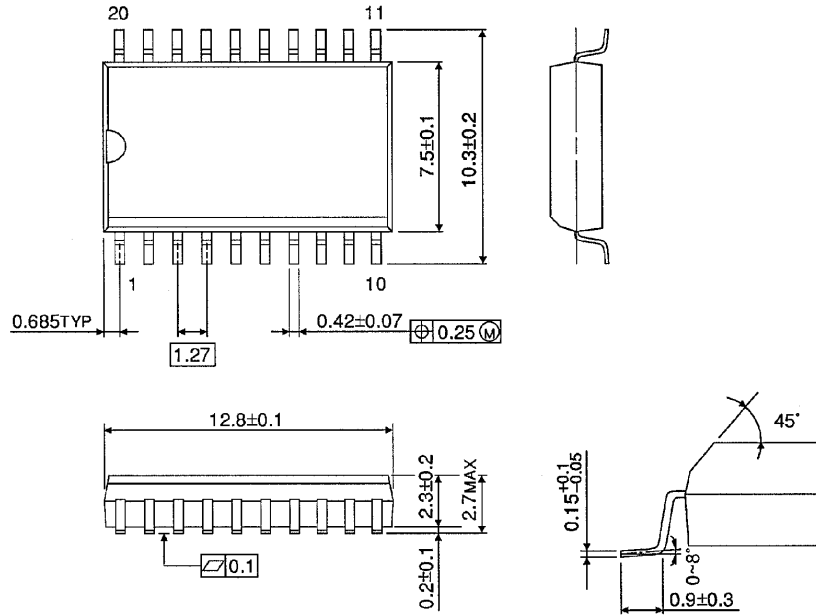
Unit in mm



**SOP 20PIN (300mil BODY) PACKAGE DIMENSIONS (SOL20-P-300-1.27)**

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.46g (Typ.)

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000707EBA

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